

*Application No. 10/673779*  
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*Amendment*  
*Attorney Docket No. 011.2B-11335-US01*

**Amendments To The Drawings:**

None.

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**Remarks**

This Amendment is in response to the Office Action dated May 31, 2005. A full three month extension is required and is requested. The filing papers specify that request and indicate payment instructions. This paper authorizes payment from the undersigned's Deposit Account in the event that the separate instructions are not received.

Independent claim 1 has been amended to recite a polishing composition including colloidal silica, an alkaline compound, a water-soluble polymer, and water. Contrastingly, Kato, et al. (U.S. 5,904,159) do not teach a polishing composition including colloidal silica. Therefore, claim 1 and claims 2-5 and 7-10, which depend directly or indirectly from claim 1, are patentable over the reference as applied in paragraph 3 of the previous office action, or Inoue, et al. (U.S. 2001/003672), in view of Kato, et al.

Newly added Independent claim 12 has been drafted to recite a polishing composition including fumed silica, an alkaline compound, a water-soluble polymer, and water. The average primary particle diameter  $D_{SA}$  of the fumed silica is from 5 to 25 nm, and the average secondary particle diameter  $D_{N4}$  of the fumed silica is from 5 to 200 nm. In other words, claim 12 corresponds to part of the subject matter of original claim 2. Original claim 2 is not rejected as being unpatentable over the Inoue, et al. in view of Kato, et al. in the outstanding office action. Therefore, claim 12 and claims 13-17, which depend directly or indirectly from claim 12, are patentable over Inoue, et al. in view of Kato et al.

Like the claimed invention, the invention of Inoue, et al. is directed to a polishing composition that is used for polishing a wafer surface. Contrastingly, the invention of Tanaka, et al. (JP 2001/118,815) is directed to a polishing composition that is used for polishing a wafer-edge. As shown in paragraph [0007] of JP 2001-118,815, the polishing of wafer edges is

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significantly different from the polishing of wafer surfaces with respect to polishing conditions including the polishing pressure and the linear velocity of the polishing pad. The polishing composition of Tanaka, et al. is a polishing composition that is modified to be expressly suitable for such a polishing of wafer edges. Therefore, there would be no motivation for a person skilled in the art to modify the polishing composition of Inoue, et al. in view of Tanaka, et al. as suggested by the Examiner. Further, neither Inoue, et al. nor Tanaka, et al. disclose or suggest that an average primary particle diameter and average secondary particle diameter of silica influence the level of haze that occurs on a wafer surface. In light of the foregoing, the claimed invention is patentable over Inoue, et al. in view of Tanaka, et al.

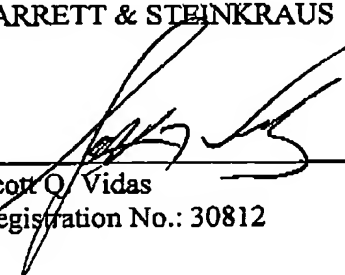
#### Conclusion

Claims 1-5, 7-10 and 12-17, as amended, and for the reasons discussed above are patentable over the cited references. A notice to that effect is earnestly solicited.

Respectfully submitted,

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